

Seminar in Computer Architecture

Meeting R2: Current Research

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25 October 2019

Understanding and Modeling On-Die Error Correction in Modern DRAM:

An Experimental Study Using Real Devices

Presented at: Dependable Systems and Networks (DSN) 2019

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Executive Summary

- **Motivation:** Experimentally studying DRAM error mechanisms provides insights for improving performance, energy, and reliability
- **Problem:** on-die error correction (ECC) makes studying errors difficult
 - Distorts true error distributions with *unstandardized, invisible* ECC functions
 - *Post-correction* errors lack the insights we seek from *pre-correction* errors
- **Goal:** Recover the *pre-correction* information masked by on-die ECC
- **Key Contributions:**
 1. **Error INference (EIN):** statistical inference methodology that:
 - Infers the ECC scheme (i.e., type, word length, strength)
 - Infers the pre-correction error characteristics beneath the on-die ECC mechanism
 - Works without any hardware intrusion or insight into the ECC mechanism
 2. **EINSim:** open-source tool for using EIN with real DRAM devices
 - Available at: <https://github.com/CMU-SAFARI/EINSim>
 3. **Experimental demonstration:** using 314 LPDDR4 devices
 - EIN infers (i) the on-die ECC scheme and (ii) pre-correction error characteristics

We hope EIN and EINSim enable many valuable studies going forward

Presentation Outline

1. Error Characterization and On-Die ECC

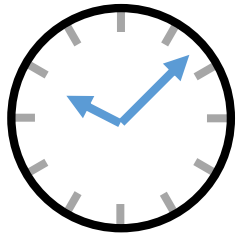
2. EIN: Error INference

- I. The Inference Problem
- II. Formalization
- III. EIN in Practice: EINSim

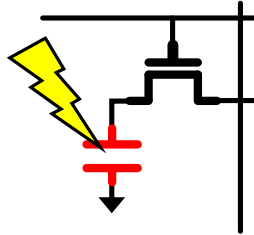
3. Demonstration Using LPDDR4 Devices

What is DRAM Error Characterization?

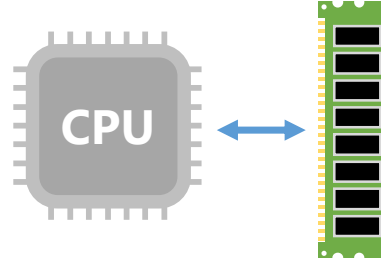
*Studying how DRAM behaves
when we deliberately induce **bit-flips***



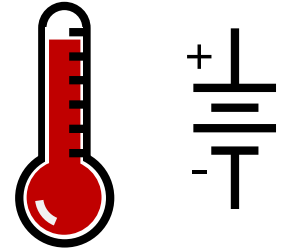
*Operating Timing
Constraints*



*Error Mechanisms
& Technology Scaling*



*System-Level
Interactions*



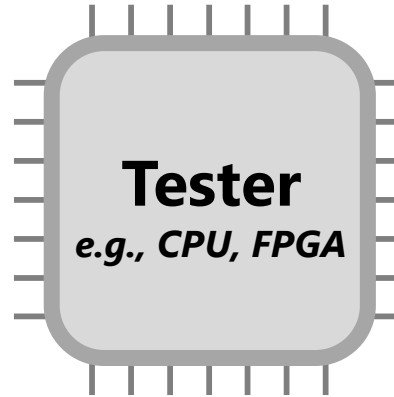
*Environmental
Effects*

**Understanding
+
Exploitable Insights**

How Do We Characterize DRAM?

Test Routine

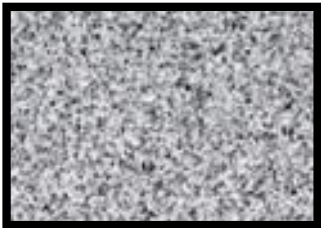
1. Write data
2. Induce errors
3. Read data
4. Record errors



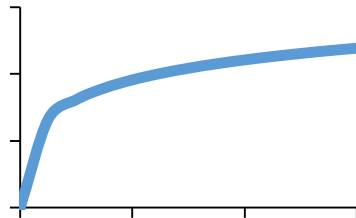
DRAM Device



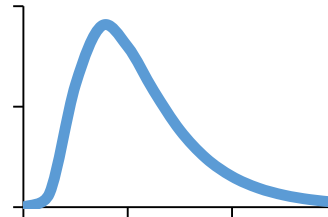
Error Distributions



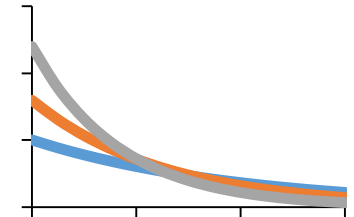
Spatial Distributions



Temporal Distributions



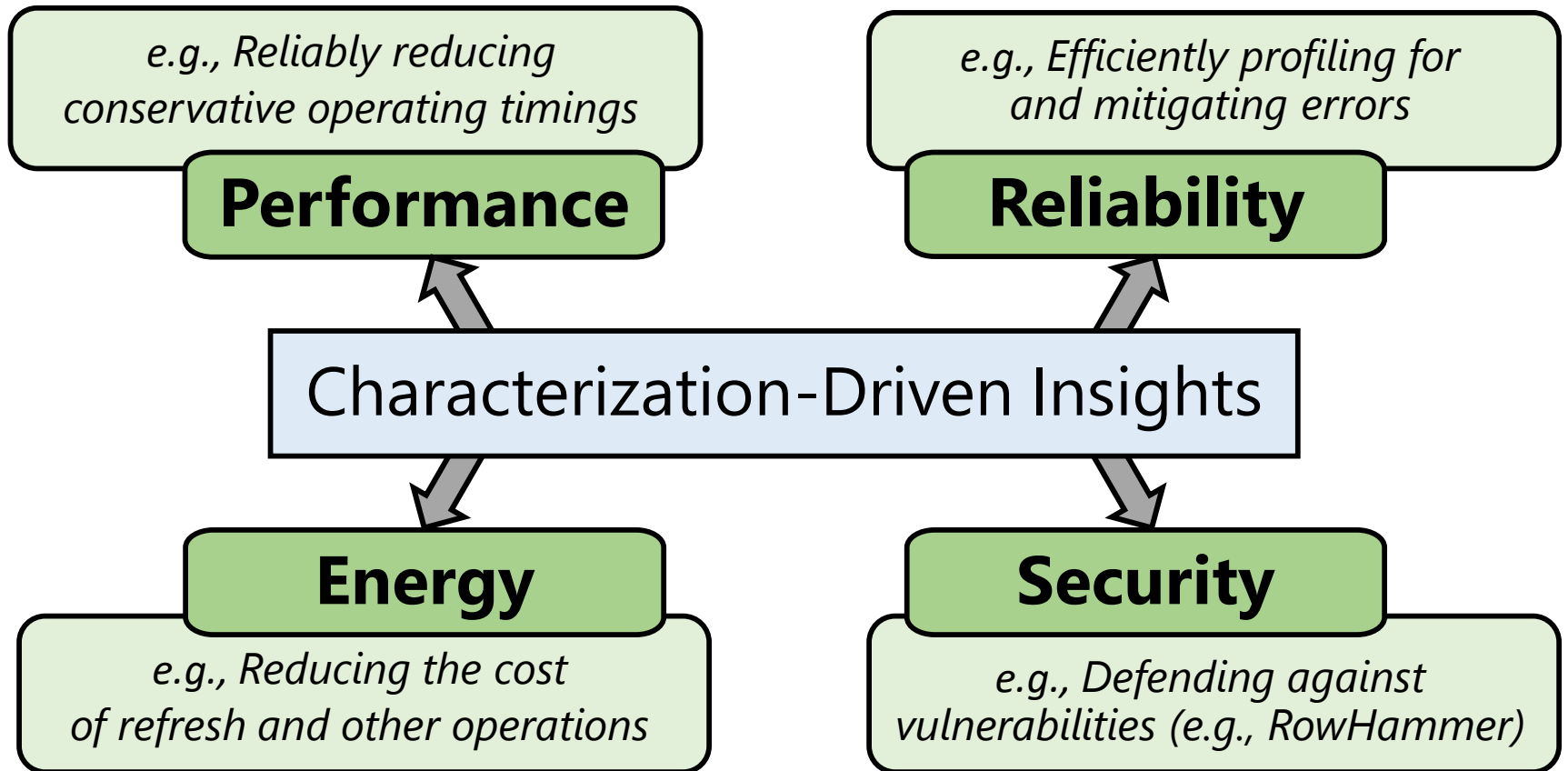
Cell-to-cell Variation



Device Comparisons

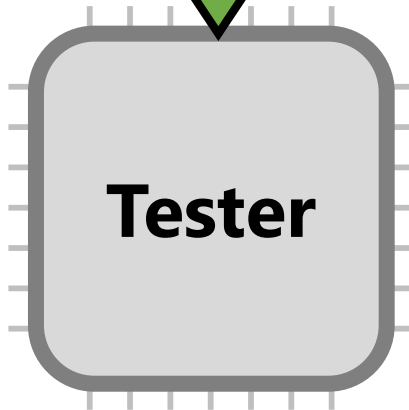
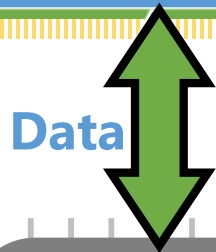
Why Study DRAM Errors?

- Errors provide insight into how a DRAM device works
 - Error mechanisms are based on physical phenomena
 - Patterns in errors can indicate opportunity for improvement

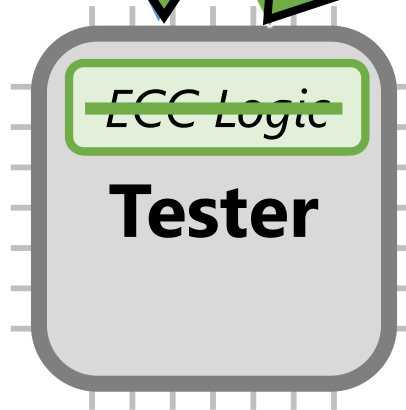
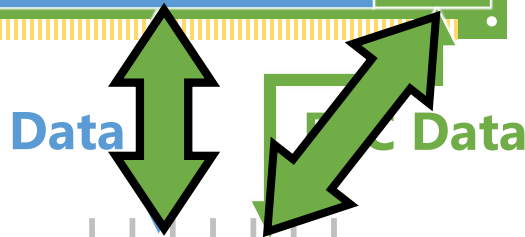
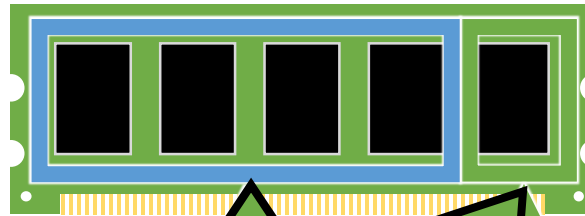


Three Key Types of DRAM

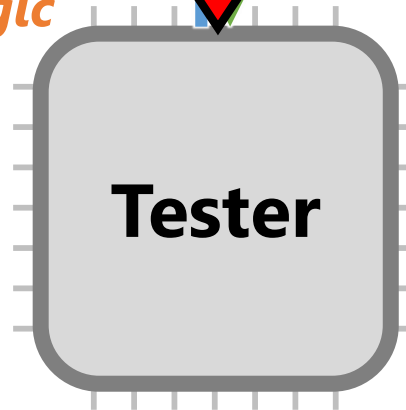
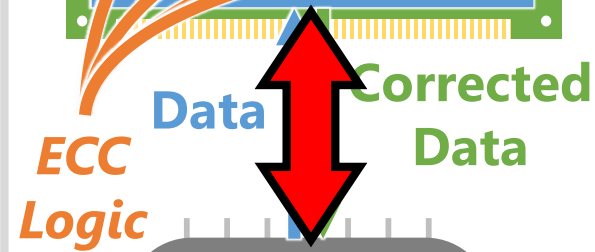
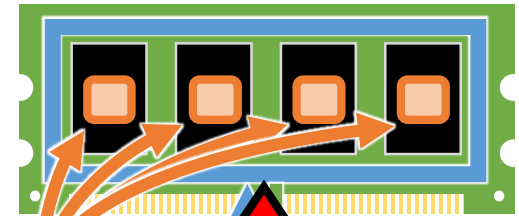
No ECC (Standard)



Rank-Level ECC (Server-style)



On-Die ECC (or Integrated ECC)



Three Key Types of DRAM

No ECC
(Standard)

Rank-Level ECC
(Server-style)

On-Die ECC
(or Integrated ECC)

Unfortunately, the on-die ECC scheme:

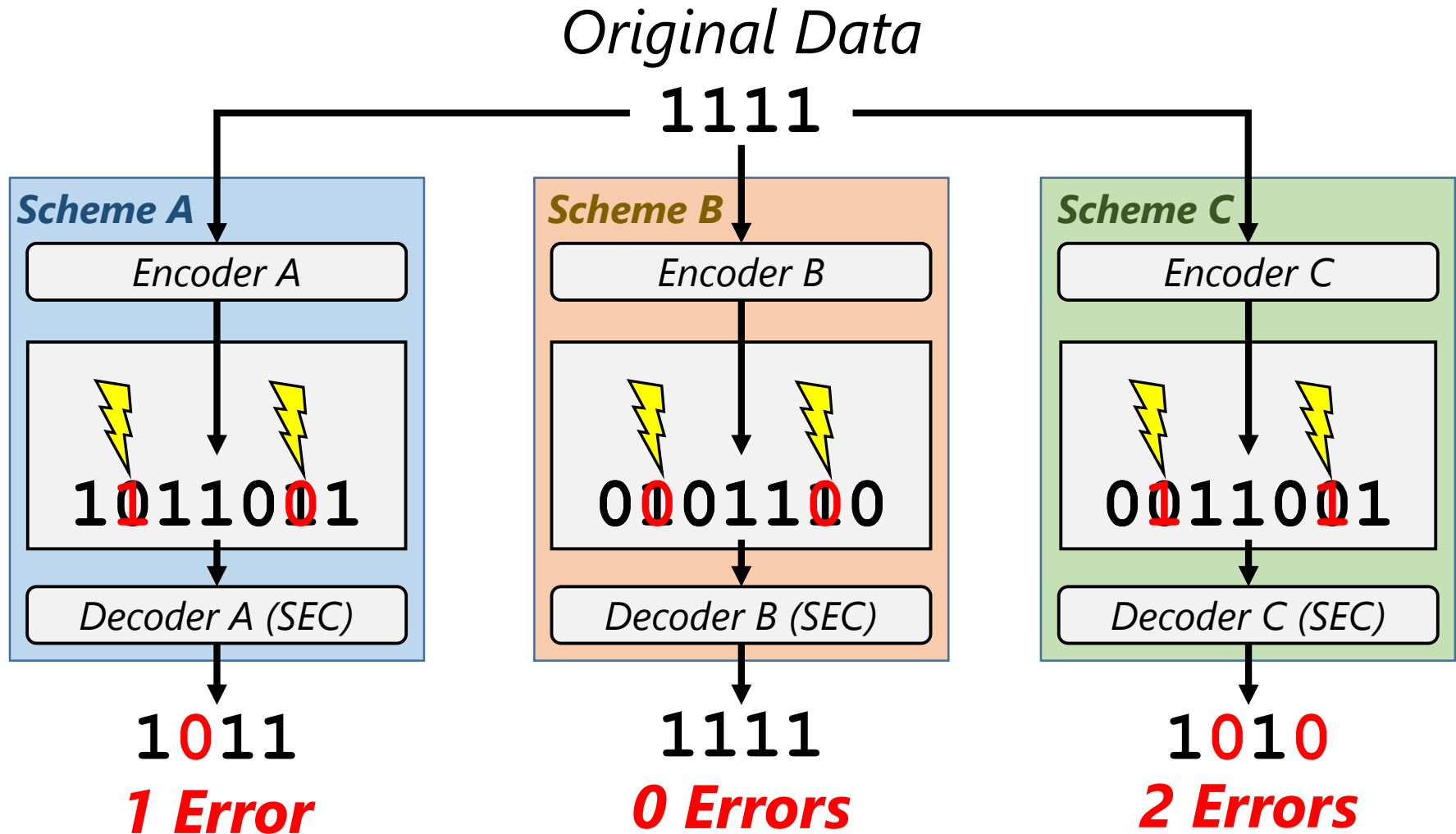
1. **Cannot** be bypassed
2. Is **unknown** and **proprietary**
3. Is completely **invisible**

✓ Raw Data Is
Unmodified

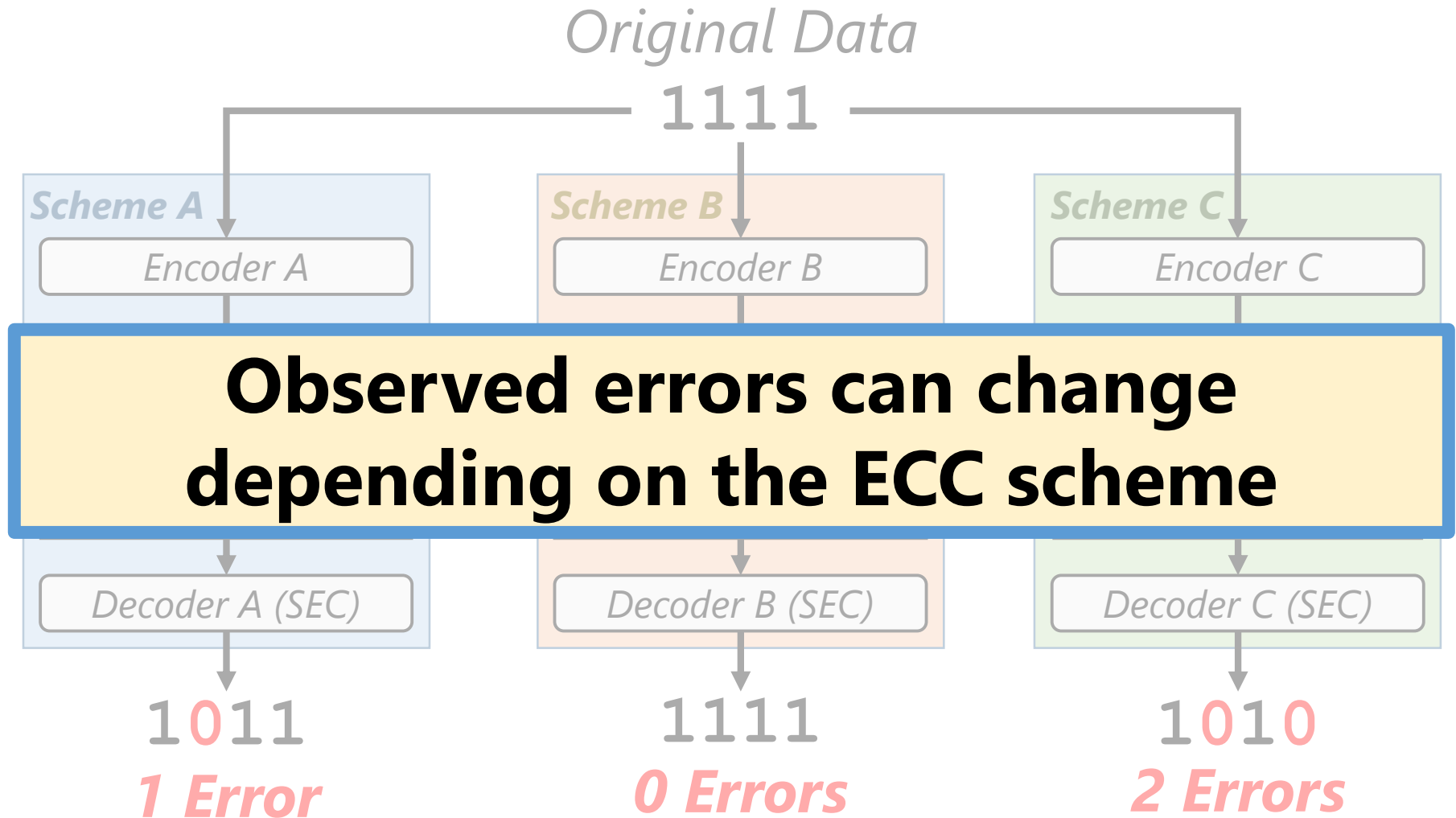
✓ Raw Data Is
Unmodified

✗ ECC Modifies
Raw Data

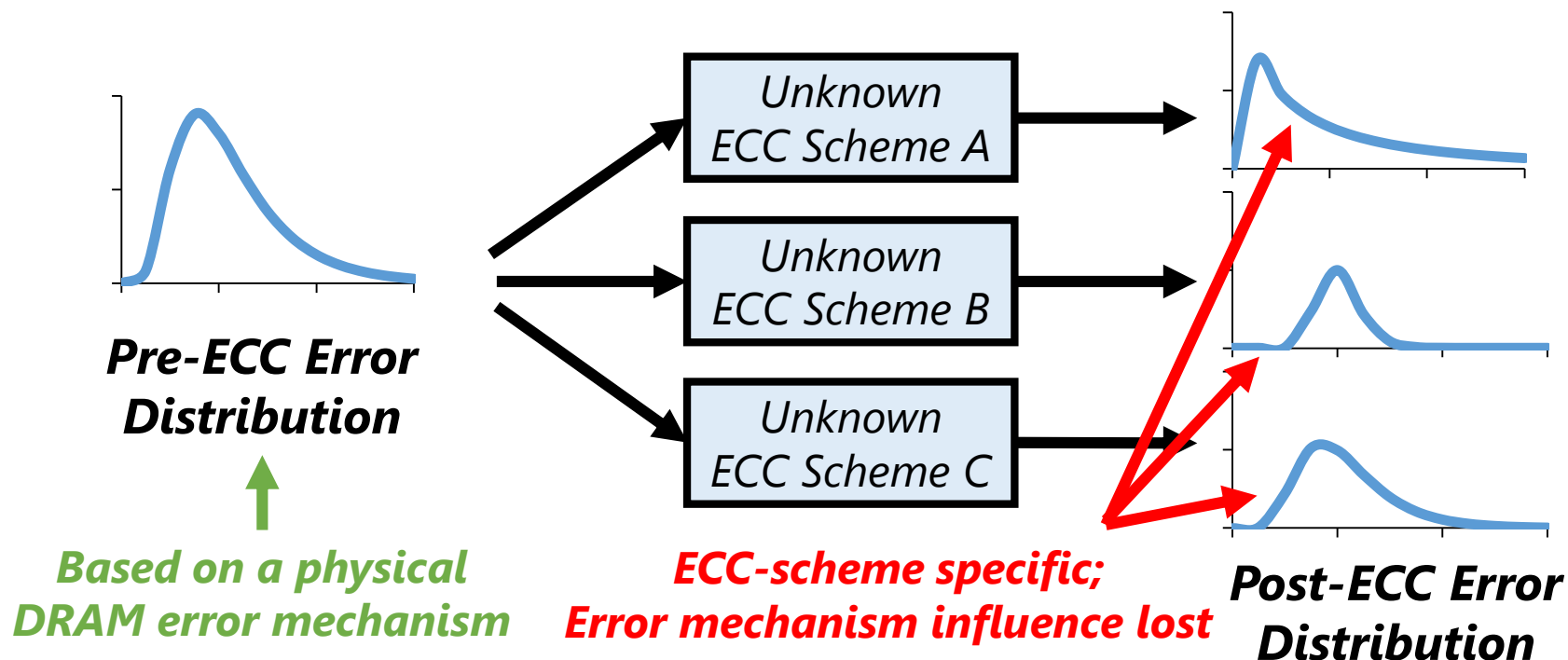
ECC Complicates Error Characterization



ECC Complicates Error Characterization



ECC Makes Error Characterization Difficult



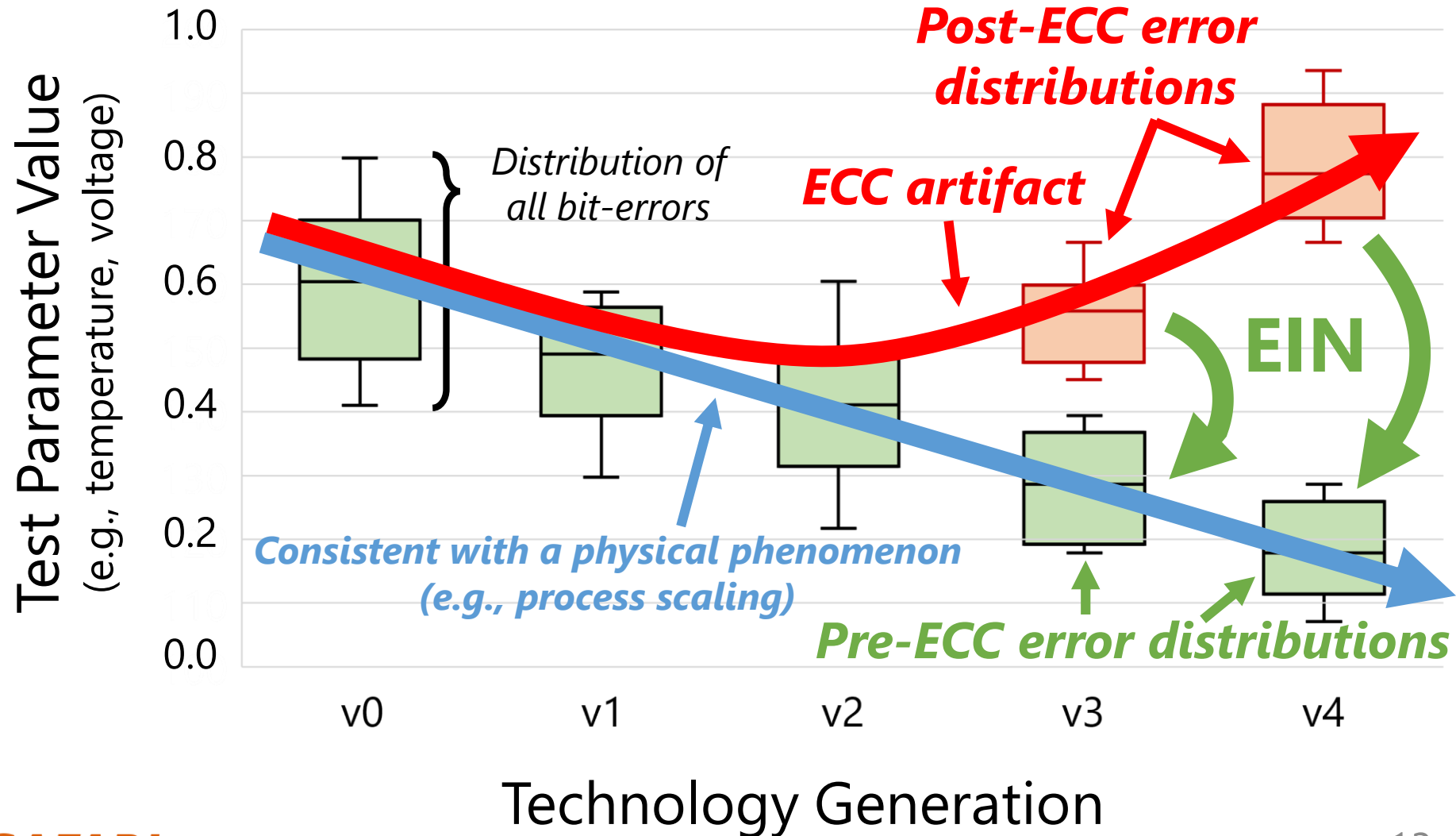
- ECC causes two key **problems**:

Prevents comparing error characteristics between devices

Obfuscates the well-studied error distributions we expect

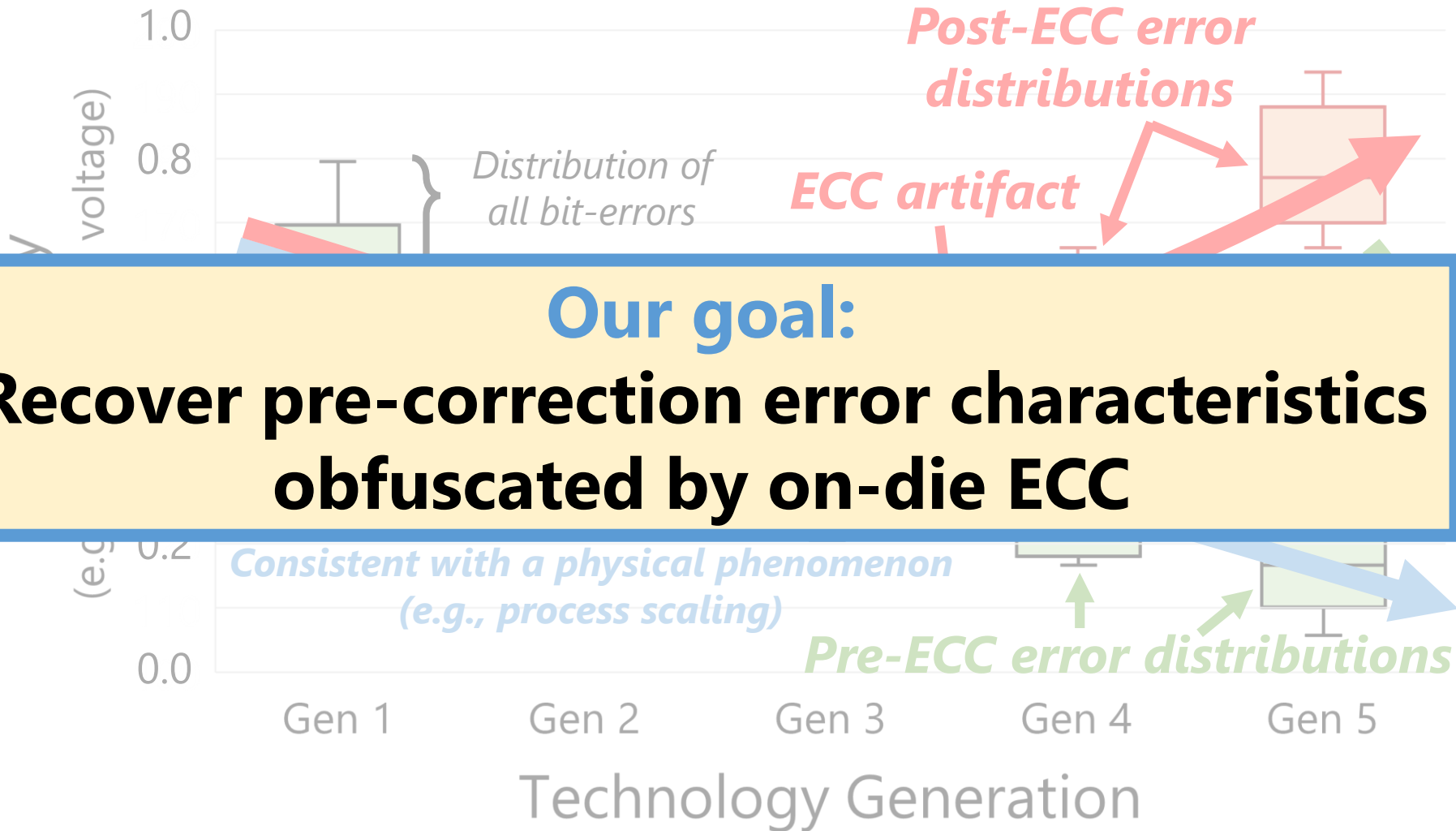
Example: Technology Scaling Study

- Goal: study how errors evolve over technology generations



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- Goal: study how errors evolve over technology generations



Presentation Outline

1. Error Characterization and On-Die ECC

2. EIN: Error INference

I. The Inference Problem

II. Formalization

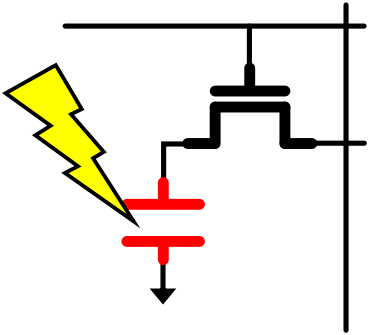
III. EIN in Practice: EINSim

3. Demonstration Using LPDDR4 Devices

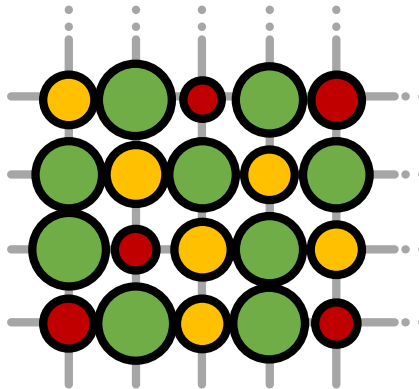
Key Observation

*DRAM error mechanisms have
predictable characteristics
that are **intrinsic** to DRAM technology*

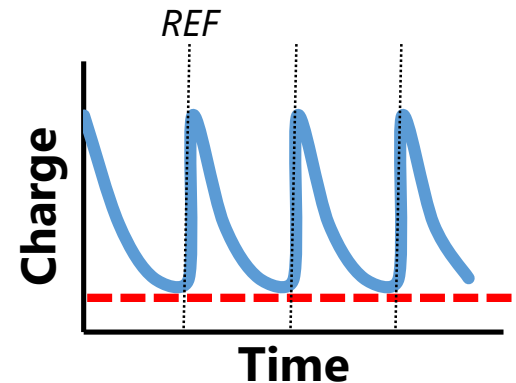
Example: Data-Retention Errors



DRAM encodes data in **leaky capacitors**



Leakage rates differ due to **process variation**

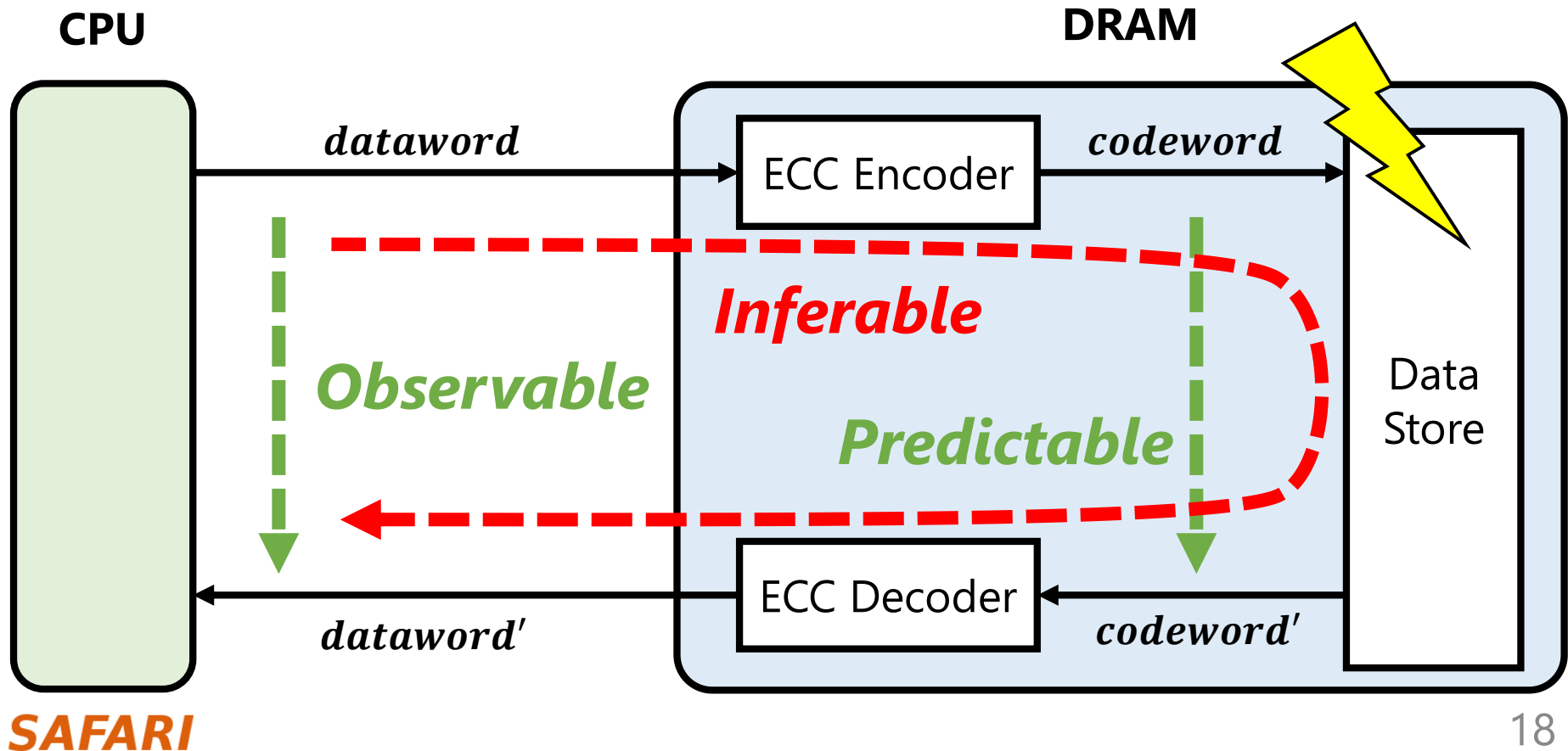


Necessitates periodic **refresh operations**

- By **disabling** refresh, we induce **data-retention errors**
- Well-studied and fundamental to DRAM technology
- Errors exhibit **predictable** statistical characteristics
 - **Exponential** bit-error rate (BER) with respect to temperature
 - **Uniform-random** spatial distribution

Inferring the ECC Scheme

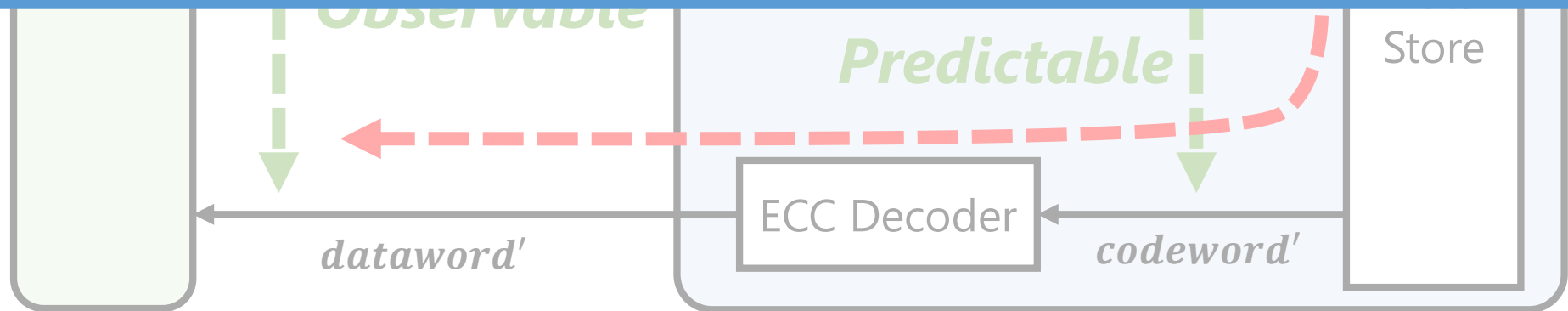
- Exploit error characteristics to **infer** the ECC scheme
 - Works for any DRAM susceptible to the error mechanism
 - Independent of any particular device or manufacturer



Inferring the ECC Scheme

- Exploit error characteristics to **infer** the ECC scheme
 - Works for any DRAM susceptible to the error mechanism
 - Independent of any particular device or manufacturer

ELN's key idea: use predictable error characteristics to infer:
(i) the ECC scheme
(ii) the pre-correction error rate



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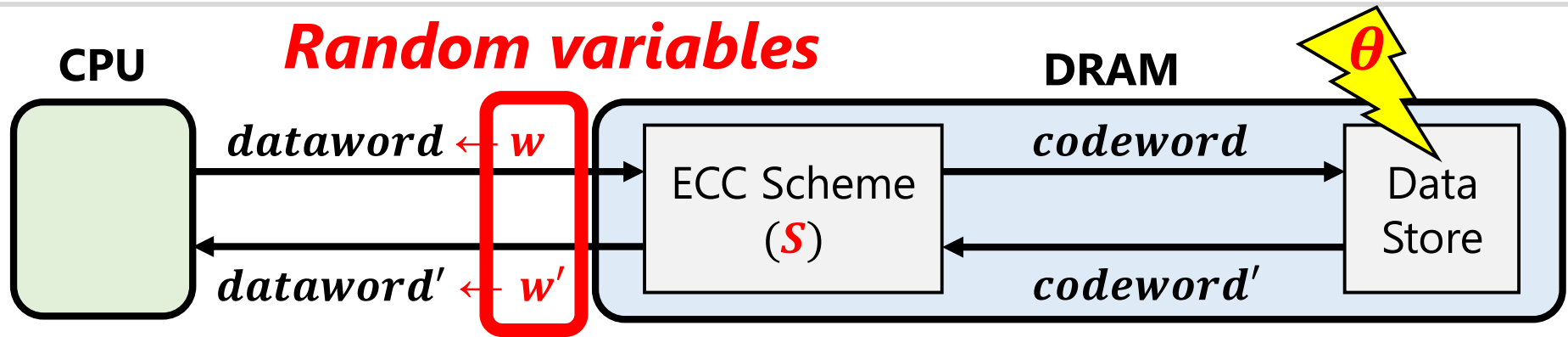
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Formalizing the Inference Problem



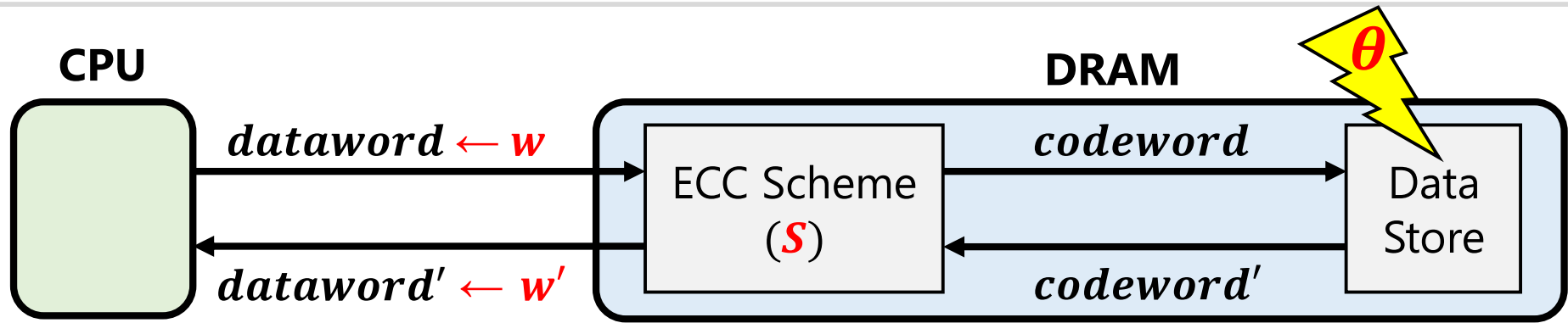
- Model the entire DRAM transformation as a **function**:

Distribution of inputs and *Distribution of outputs* are indicated by blue arrows pointing to the function $w' = f(w | S, \theta)$. The function is also influenced by the *ECC Scheme* (S) and the *Error Distribution* (θ), as indicated by blue arrows.

$$w' = f(w | S, \theta)$$

We want to **infer** $\{S, \theta\}$ given **observed** $\{w, w'\}$

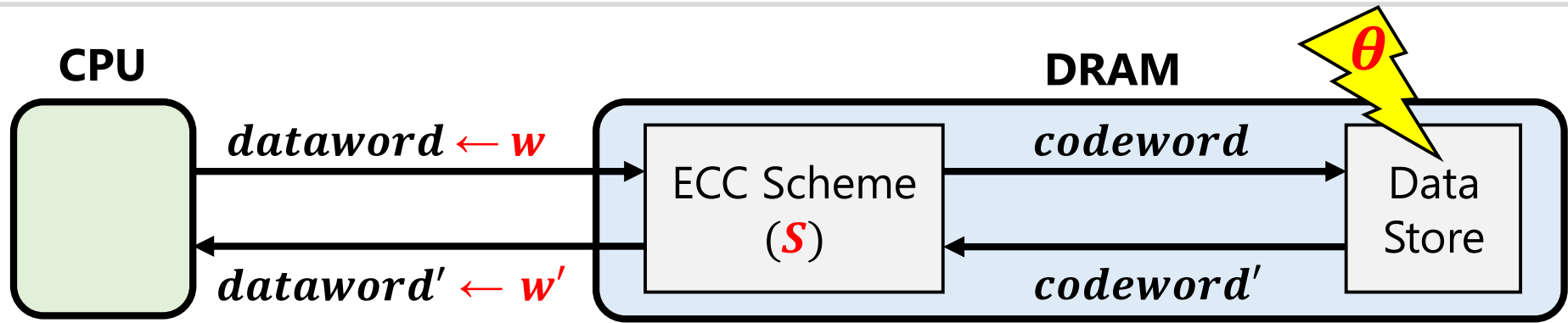
Formalizing the Inference Problem



$$w' = f(w \mid S, \theta)$$

- S : ECC encoding/decoding algorithms
- θ : Spatial distribution of errors (e.g., uniform-random)
- w, w' : Probability of each value (i.e., $0x0, 0x1, \dots$)
 - w is typically defined by the **data pattern** we write

Formalizing the Inference Problem

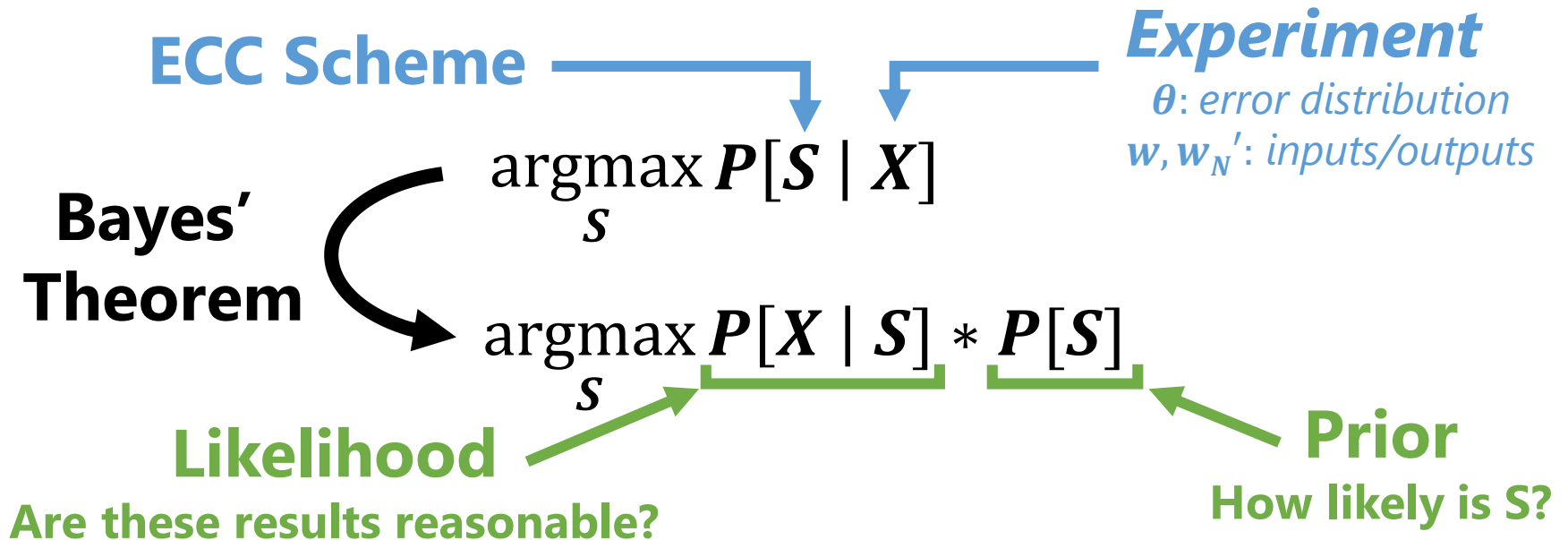


$$w' = f(w \mid S, \theta)$$

- **Unfortunately:** w' is hard to measure
 - 64-bit *dataword* $\rightarrow 2^{64}$ possible values
 - Typical 8GiB DRAM only has $\sim 2^{30}$ *datawords* ($\ll 2^{64}$)
 - Hard to get a representative sample of w' even with all 8GiB
- w'_N : Probability that w' has $N \in [0, 1, \dots, n]$ errors
 - Easy to experimentally measure: simply count errors
 - Meaningful in the context of ECC (e.g., n -error correction)

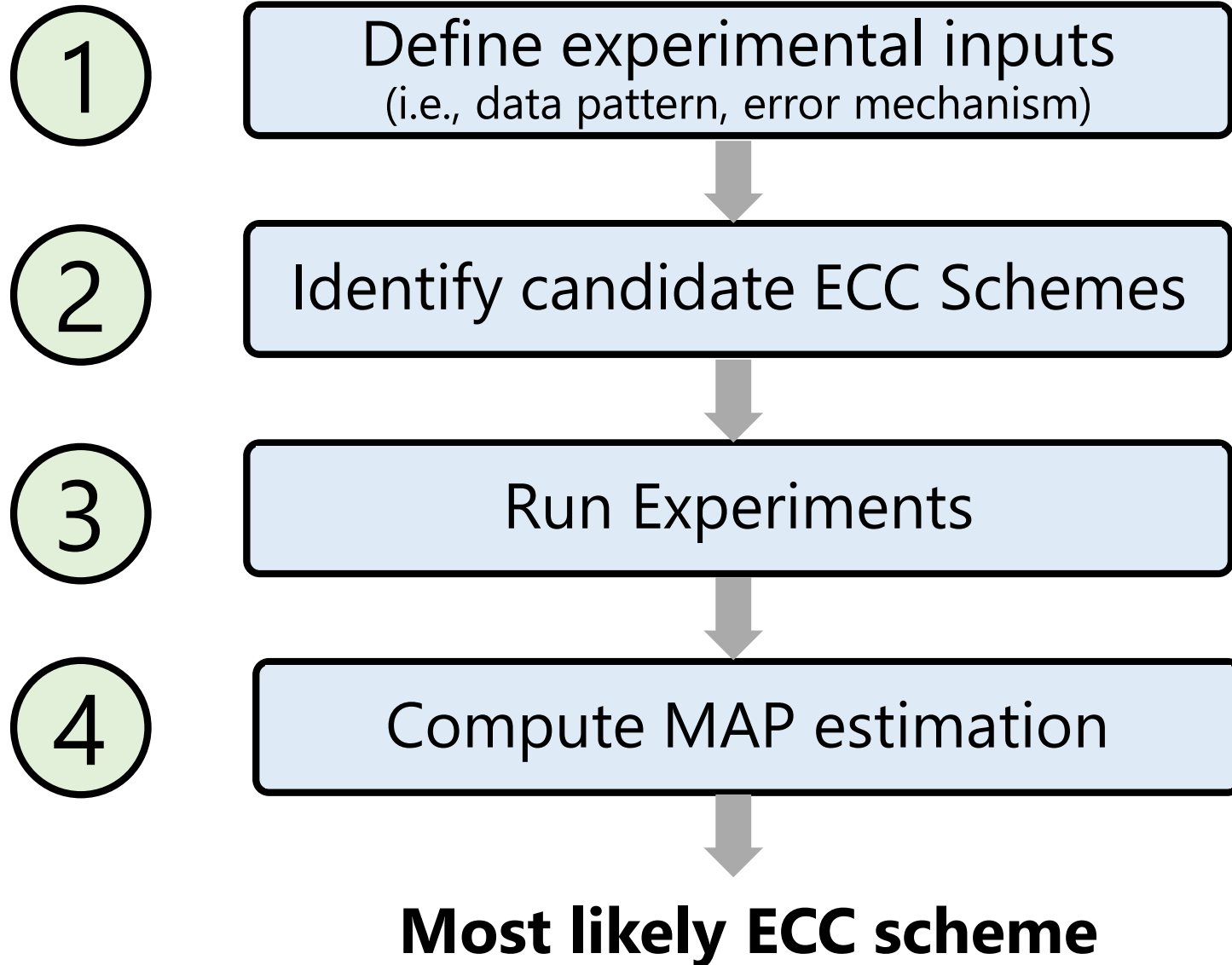
Inferring the ECC Scheme

Want the **most likely** ECC scheme **given** an experiment



- This is a **maximum-a-posteriori** (MAP) estimation
- We provide a rigorous derivation in the paper
 - Full optimization objective function
 - **Extension** for inferring error distribution characteristics θ

Error INference (EIN) Methodology



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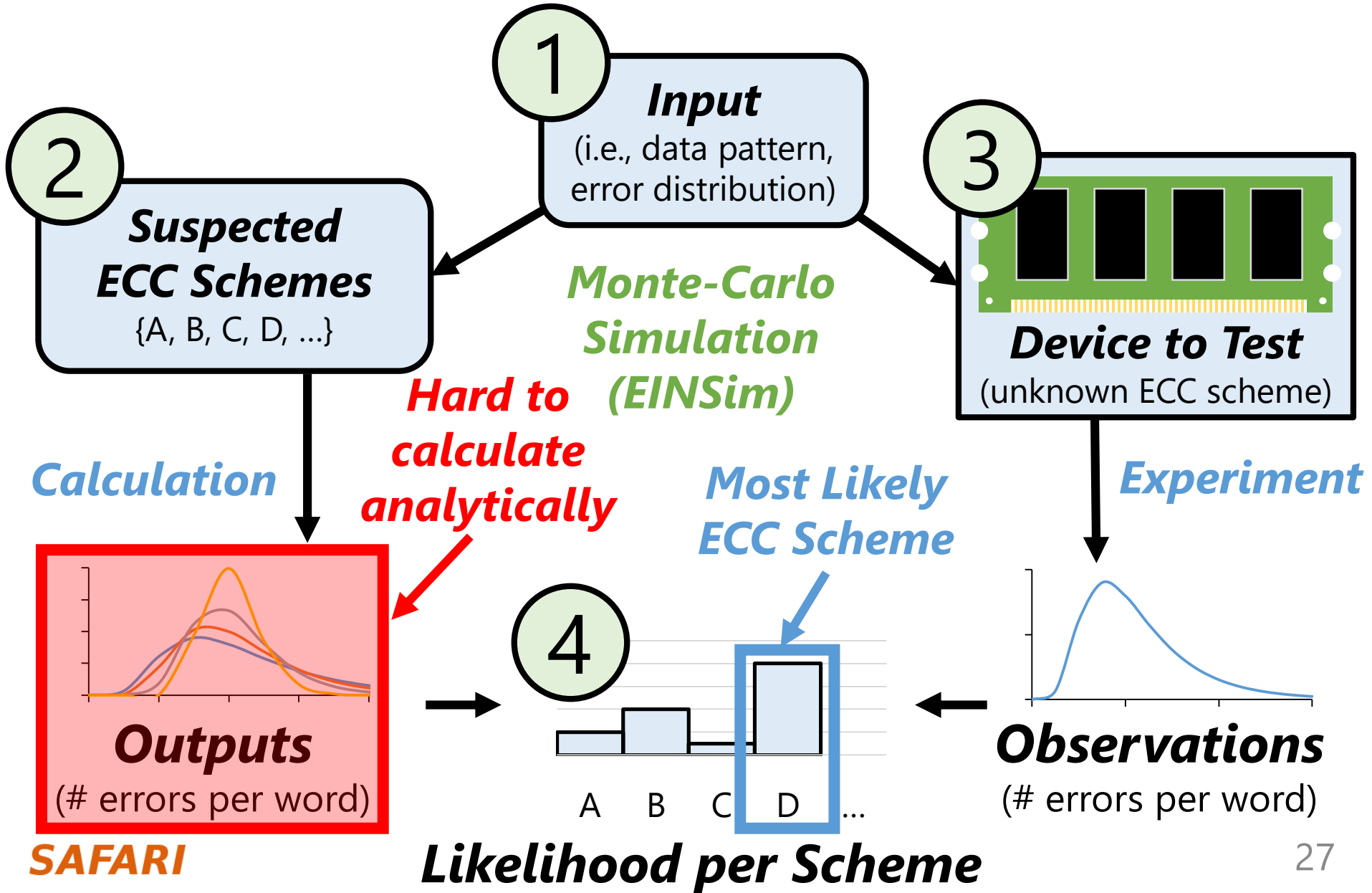
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MAP Estimation in Practice



EINSim: A Tool for Using EIN

- Evaluates MAP estimation via Monte-Carlo simulation
 - Simulates the life of a dataword through a real experiment
 - Configuration knobs to replicate the experimental setup
- Flexible and extensible to apply to a wide variety of:
 - DRAM devices
 - Error mechanisms
 - ECC schemes

Open-source C++/Python project

<https://github.com/CMU-SAFARI/EINSim>

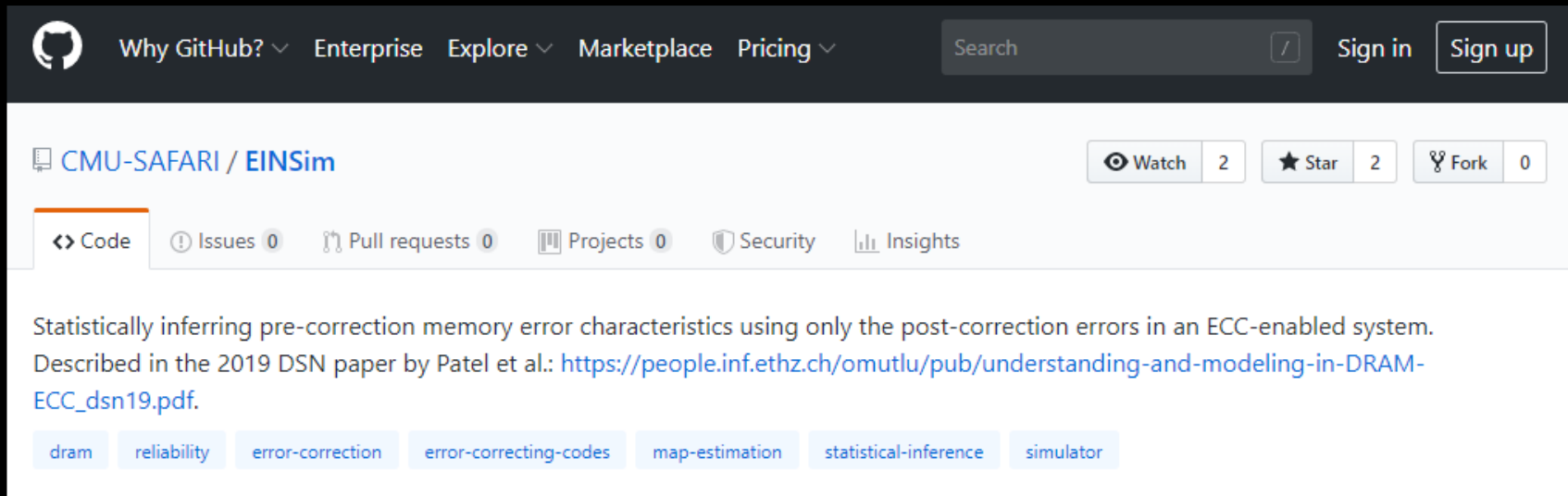
- Example datasets provided (same as used in paper)

EINSim: A Tool for Using EIN

- Evaluates MAP estimation via Monte-Carlo simulation

Give EINSim a try at:

<https://github.com/CMU-SAFARI/EINSim>



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Methodology

- We experimentally test LPDDR4 DRAM devices
 - 232 **with** on-die ECC (one major manufacturer)
 - 82 **without** on-die ECC (three major manufacturers)
- Thermally controlled testing chamber
 - 55°C - 70°C
 - Tolerance of $\pm 1^\circ\text{C}$
- Precise control over the commands sent to DRAM
 - Ability to enable/disable self-/auto-refresh
 - Control over CAS (i.e., read/write) commands

Experimental Design

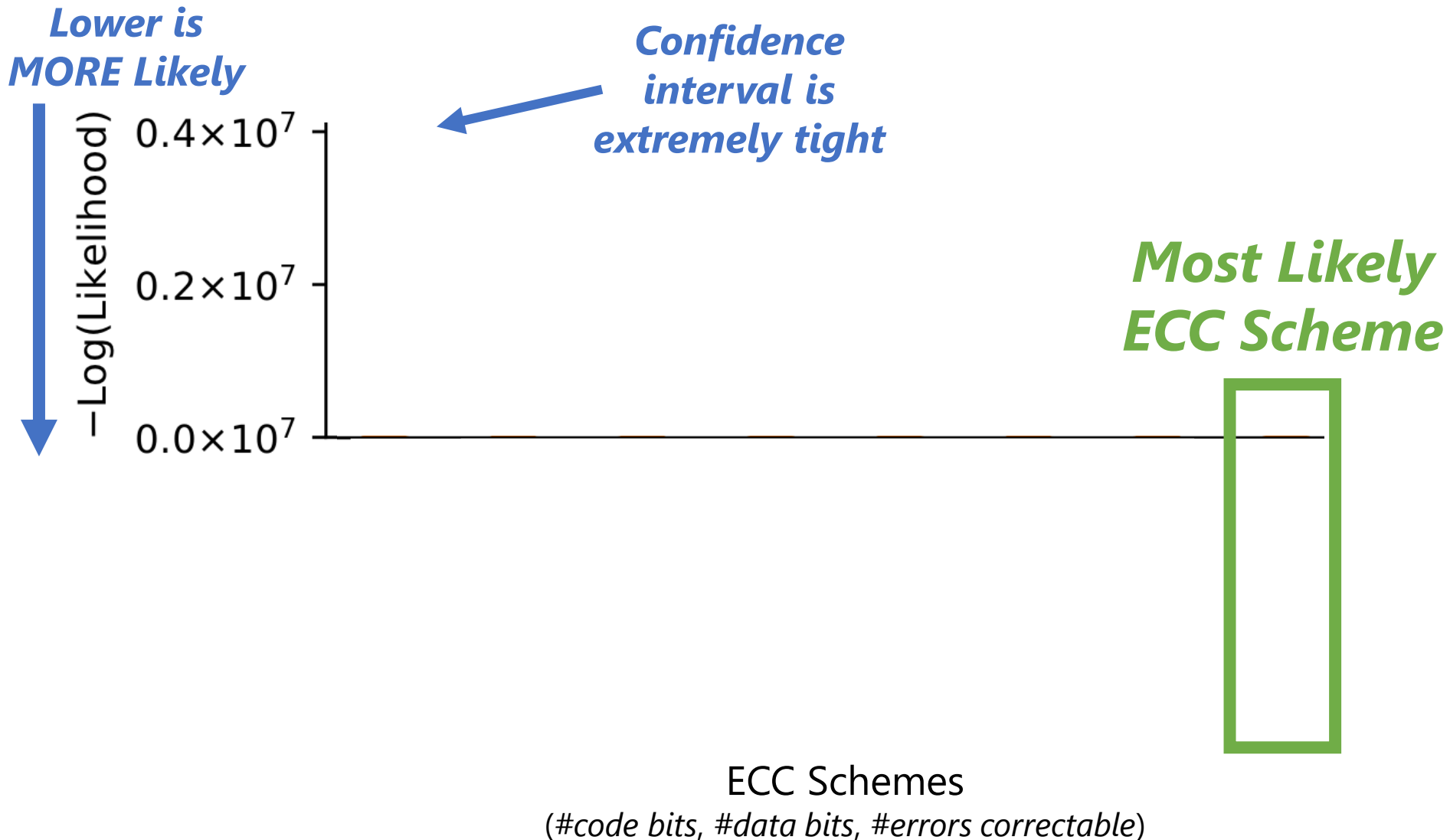
Goal: infer which ECC scheme is used
in real LPDDR4 devices with on-die ECC

<i>Parameter</i>	<i>Experiment</i>	<i>Simulation (EINSim)</i>
Word Size	256 bits	256 bits
ECC Schemes	Unknown	Hamming (32, 64, 128, 256) BCH-2EC (32, 64, 128, 256) BCH-3EC (32, 64, 128, 256) Repetition (3, 5, 7)
Data Pattern	RANDOM	RANDOM, 0xFF
Error Mechanism	Data-Retention	Data-Retention

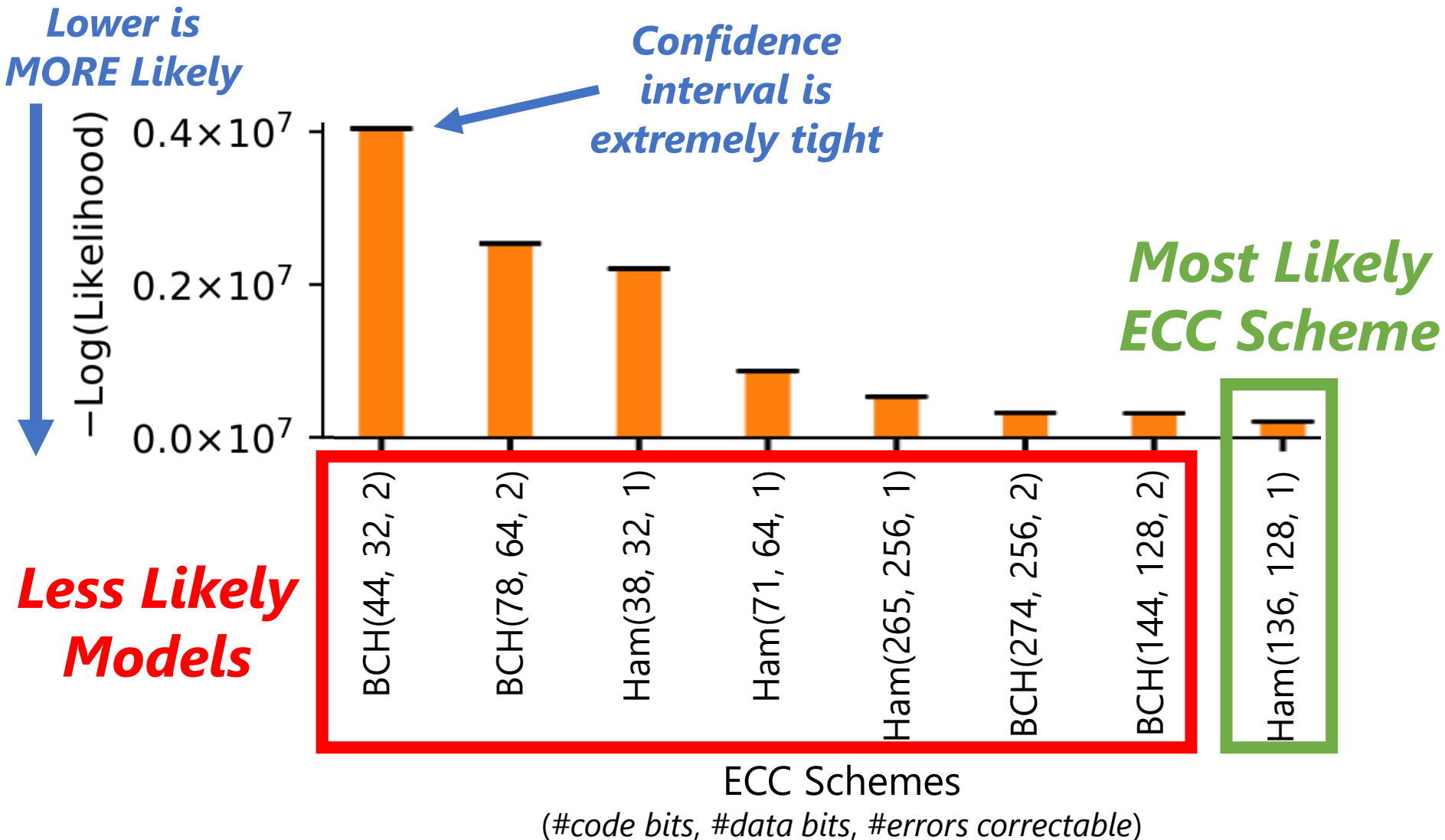
MAP Estimation Methodology

- Assume a uniform prior distribution
 - Avoids biasing results towards our preconceptions
 - Demonstrates EIN in the worst case
- Simulate 10^6 256-bit words per ECC scheme
- Error estimation using bootstrapping (10^4 samples)

MAP Estimation Results



MAP Estimation Results



MAP Estimation Results

Lower is

Confidence

EIN effectively infers the ECC scheme in LPDDR4 devices with on-die ECC to be a (128 + 8) Hamming Code

EIN infers the ECC scheme without:

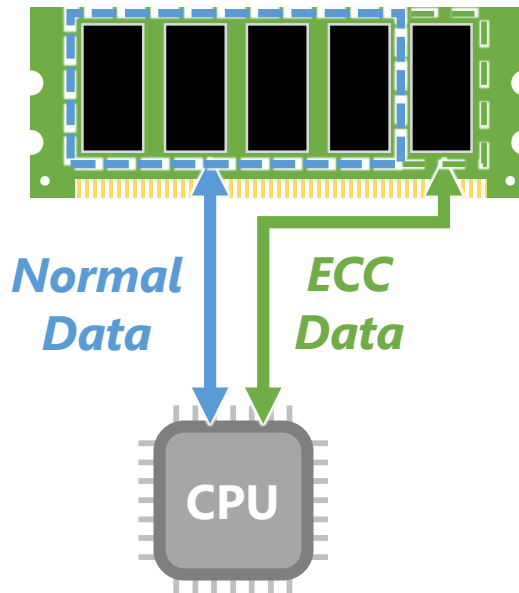
- **Visibility into the ECC mechanism**
- **Disabling ECC**
- **Tampering with the hardware**

(#code bits, #data bits, #errors correctable)

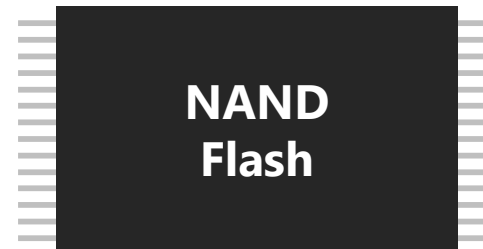
EIN Applies Beyond On-Die ECC

- EIN technically applies for *any* device for which:
 - Communication channel protected by ECC
 - Can induce uncorrectable errors
 - Errors follow predictable statistical characteristics

DRAM Rank-Level ECC



Flash Memory ECC



Other Contributions in our Paper

- Two error-characterization studies showing EIN's value
 1. EIN enables comparing BERs of the DRAM technology itself
 2. EIN recovers expected distributions that ECC obfuscates
- Using EIN to infer additional information:
 - The data pattern written to DRAM
 - The pre-correction error characteristics (e.g., pre-ECC BER)
- Formal derivation of EIN + discussion of its limitations
- Verify uniform-randomly spaced data-retention errors
 - Reverse-engineering DRAM design characteristics that affect uniformness (e.g., true-/anti-cell layout)

Talk & Paper Recap

- **Motivation:** Experimentally studying DRAM error mechanisms provides insights for improving performance, energy, and reliability
- **Problem:** on-die error correction (ECC) makes studying errors difficult
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Backup Slides

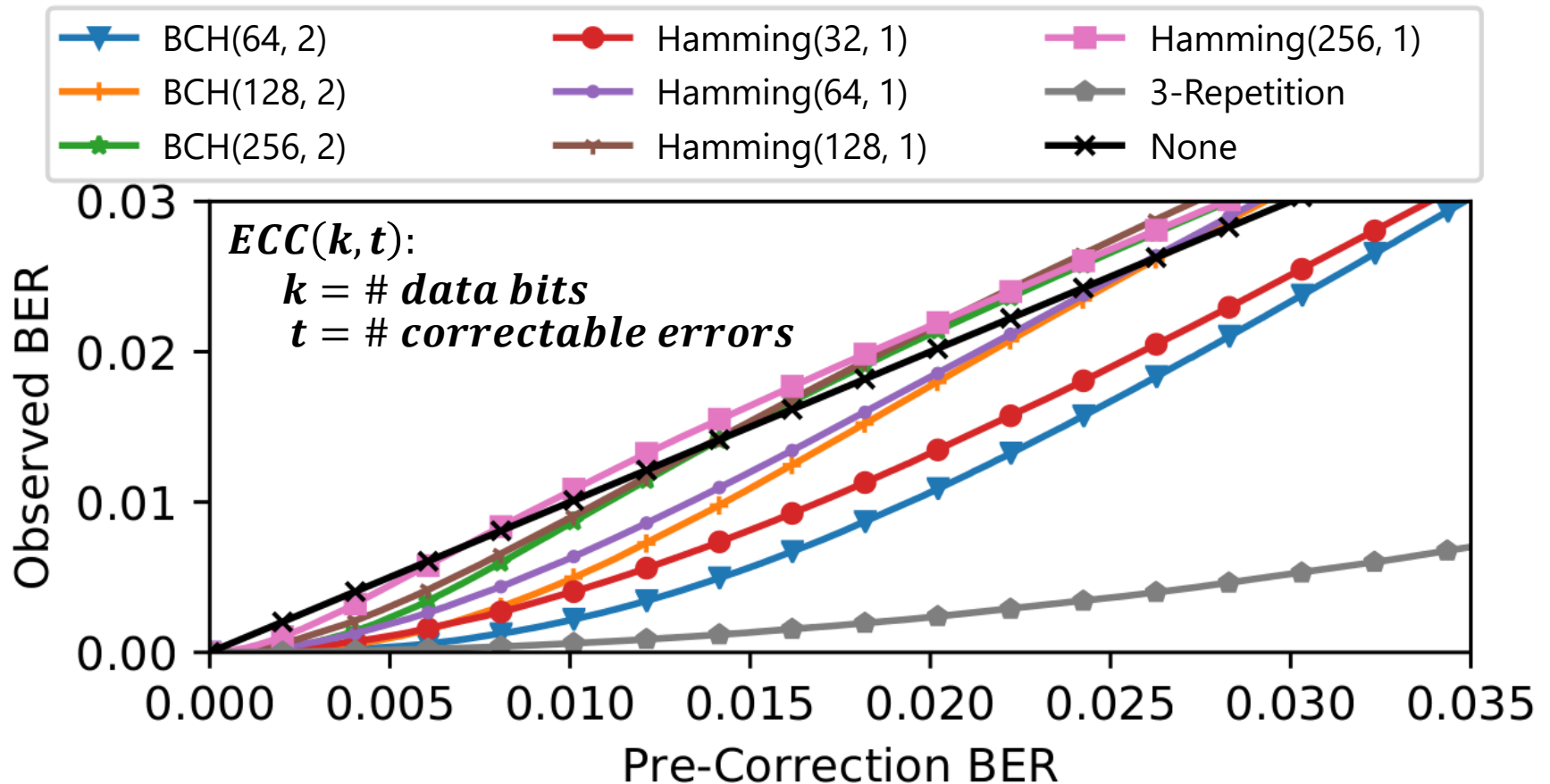
EIN: 3 Concrete Use Cases

1. Rapid error profiling using statistical distributions
 - Use properties of the *error mechanisms* to model errors
 - Use EIN to determine model parameters at runtime
 - Replacement for laborious, per-device characterization
2. Comparison studies (e.g., technology scaling)
 - Use EIN to compare *pre-correction* error rates
 - Study + predict industry and future technology trends
3. Reverse-engineering proprietary ECC schemes
 - Applies beyond just DRAM with on-die ECC
 - Can be useful for security research
 - E.g., vulnerability evaluation, patent infringement, competitive analysis, forensic analysis

Observed BER Depends on ECC

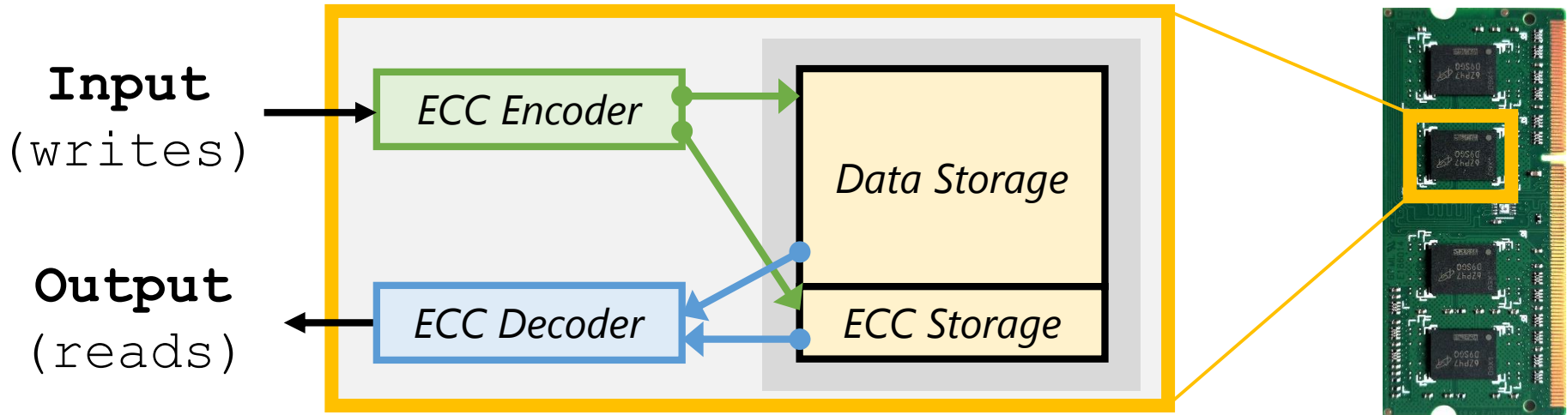
Assume errors occur independently, uniform-randomly

- Fixed per-bit $P[\text{error}] = \text{"bit error rate"} \text{ (BER)}$



A Closer Look at On-Die ECC

DRAM with on-die ECC



Primarily mitigates technology scaling issues [1]

- Transparently mitigates random single-bit errors (e.g., VRT)
- Fully backwards compatible (no changes to DDRx interface)

Unfortunately, has side-effects for error characterization

- Unspecified, black-box implementation
- Obfuscates errors in an ECC-specific manner

On-Die ECC in Literature

- Two types of ECC mentioned
 - (128 + 8) Hamming code
 - (64 + 7) Hamming code
- Paper contains references to both of these

On-Die ECC Research Challenge

Good for DRAM manufacturers:

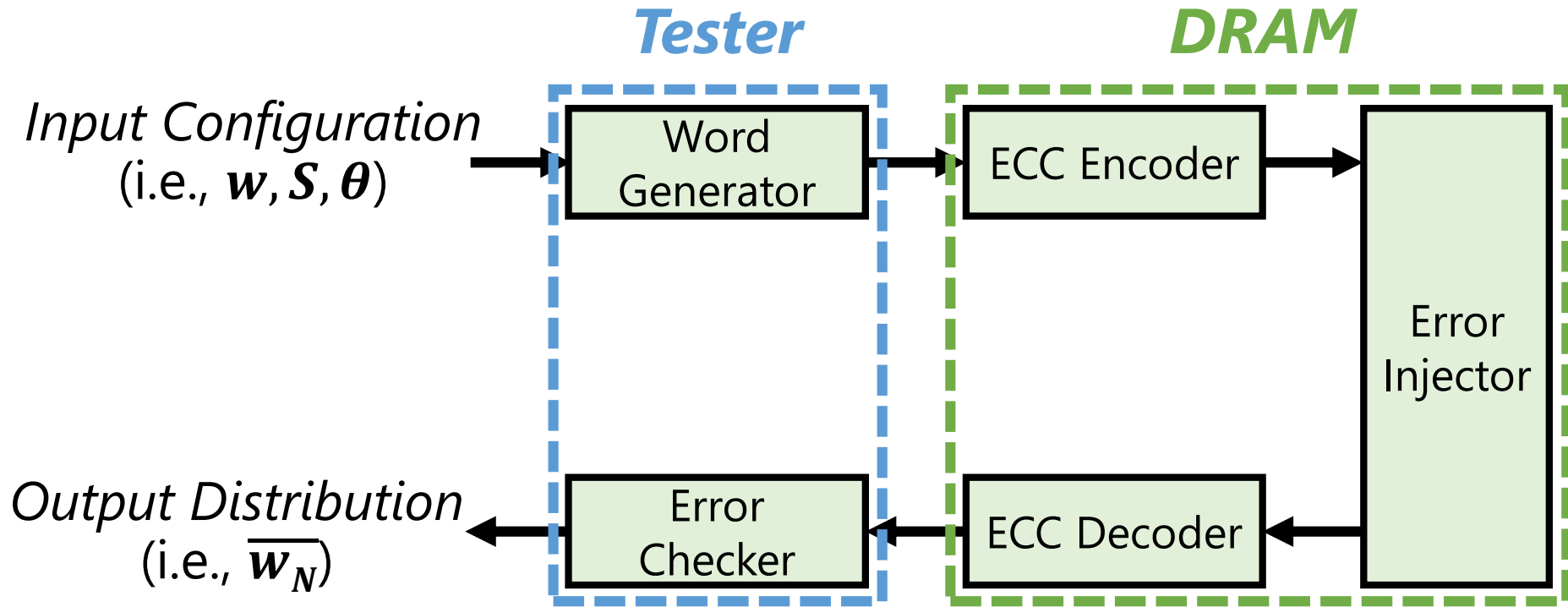
- ✓ Transparently improves reliability
- ✓ Decreases power required for data retention
- ✓ Low latency/power overhead
- ✓ No changes to DRAM interface (i.e., backwards compatible)

Bad for researchers studying DRAM errors:

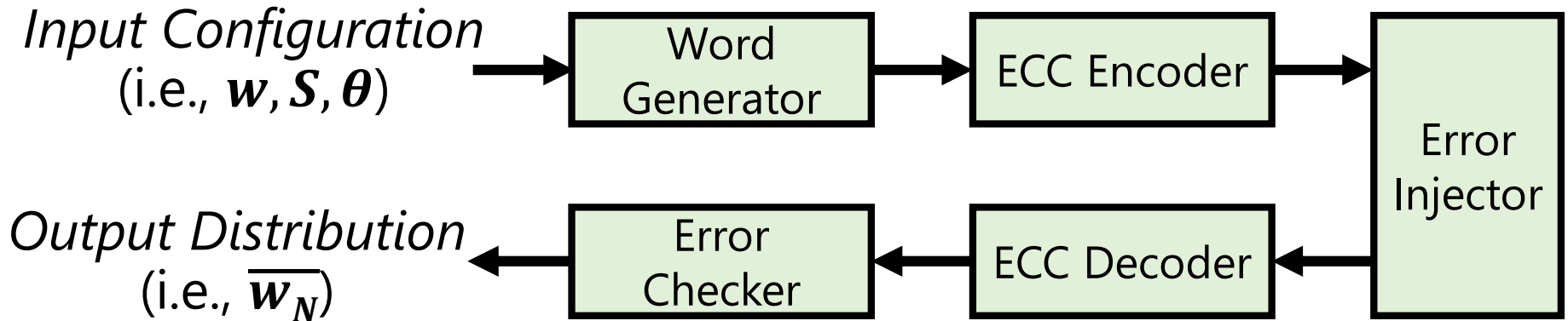
- ✗ Hides errors in a black-box, device-specific way
- ✗ Distorts well-understood statistical distributions
- ✗ Prevents fairly comparing BER of the DRAM itself

EINSim Functional Description

- Simulates the dataflow through a real experiment
 - Configuration parameters replicate experimental setup
 - Simulate enough words to resolve the output distribution

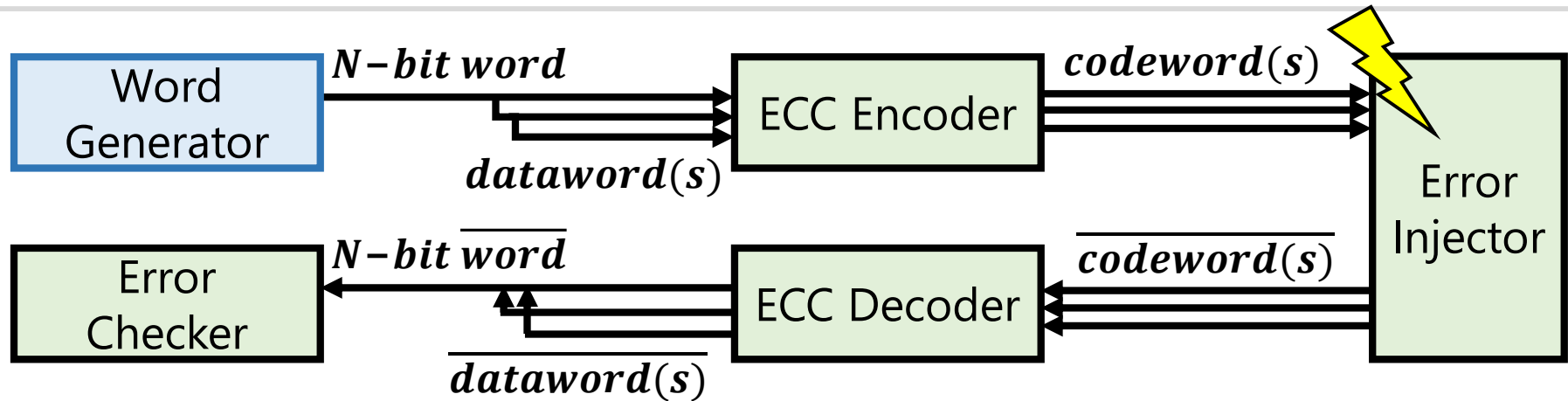


EINSim Configuration + Features



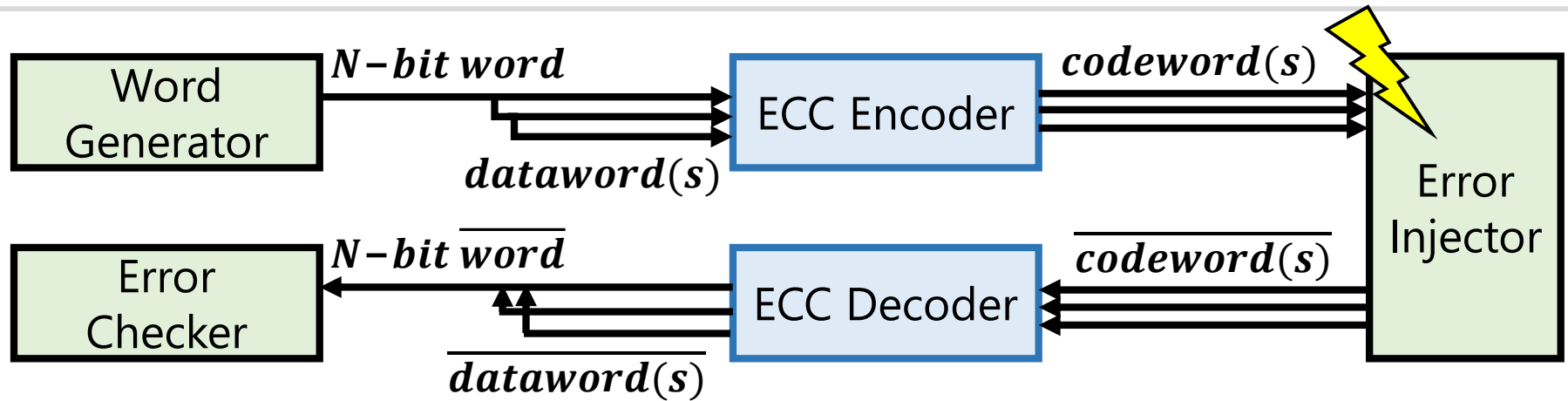
<i>Module</i>	<i>Parameters</i>
Word Generator	Word length Data Pattern
ECC Encoder, ECC Decoder	ECC code {type, length, strength} code details (e.g., generator polynomial)
Error Injector	Spatial error distribution
Error Checker	Measurement (e.g., #errors per word)

Word Generator



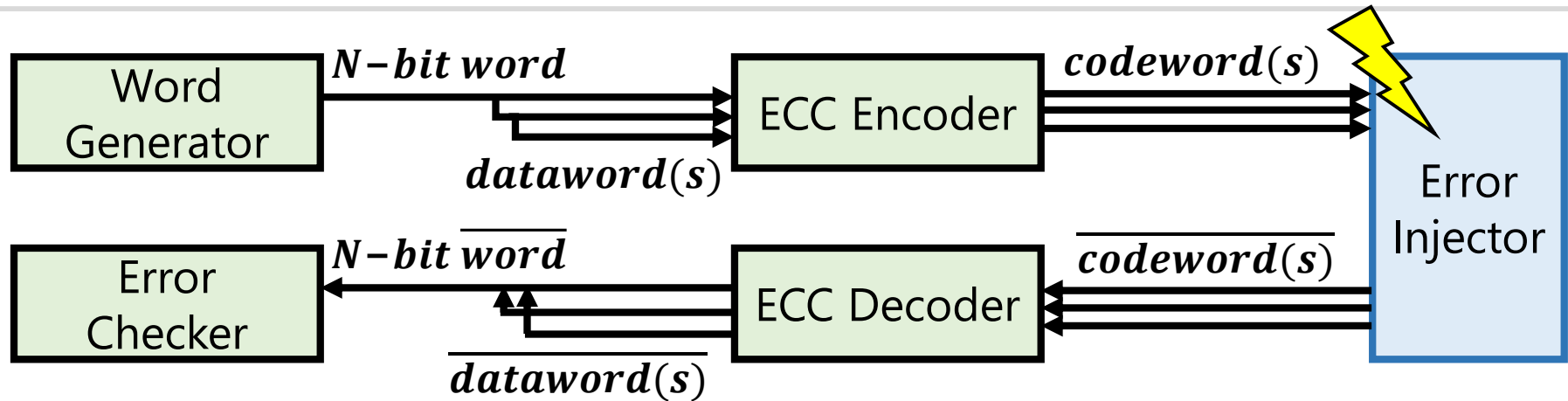
- Creates an *N-bit word*
 - Commonly used data patterns (e.g., **0xFF**, **RANDOM**)
 - Effectively sampling the *w* distribution
- N may be multiple *datawords* long
 - Useful if we don't know how *datawords* are laid out
 - Split into *datawords* according to a configurable mapping
 - More details about this in the paper

ECC Encoder/Decoder



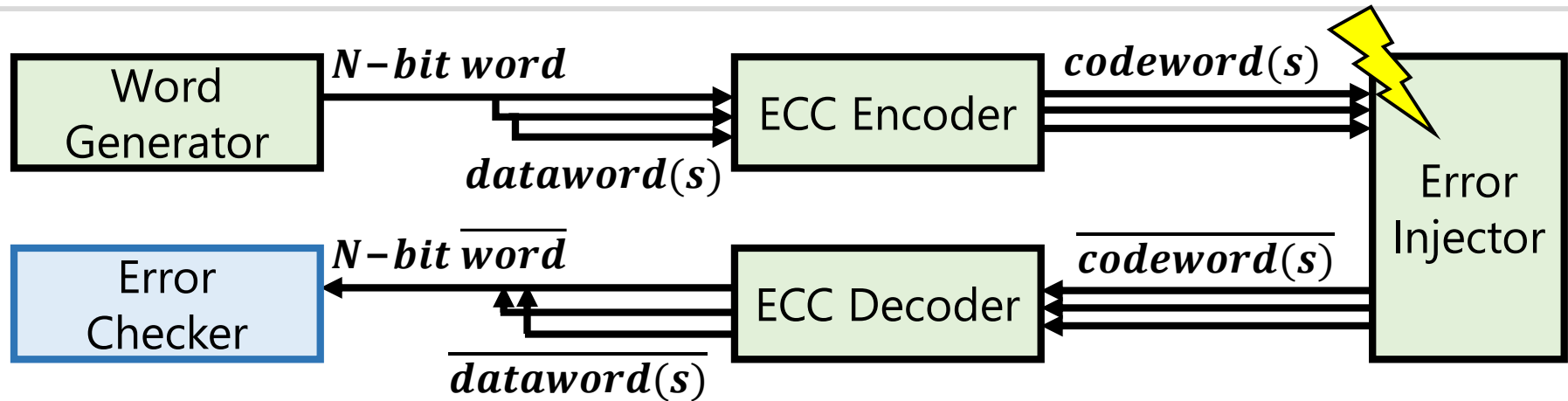
- EINSim implements ECC algorithms
 - Currently supports common codes (e.g., Hamming, BCH)
 - Modularly designed and easily extensible to others
 - Validated by hand + using unit tests (available on GitHub)
- Configurable parameters for:
 - Number of data bits, correction capability
 - Details of implementation (e.g., generator polynomials)

Error Injector



- Injects errors according to a spatial error distribution
 - Configurable parameters depend on particular distribution
 - Extensible to many different error distributions
- Uniform-random for data-retention errors
 - We experimentally validate this using real LPDDR4 devices
 - Experiment and analysis discussed in detail in the paper

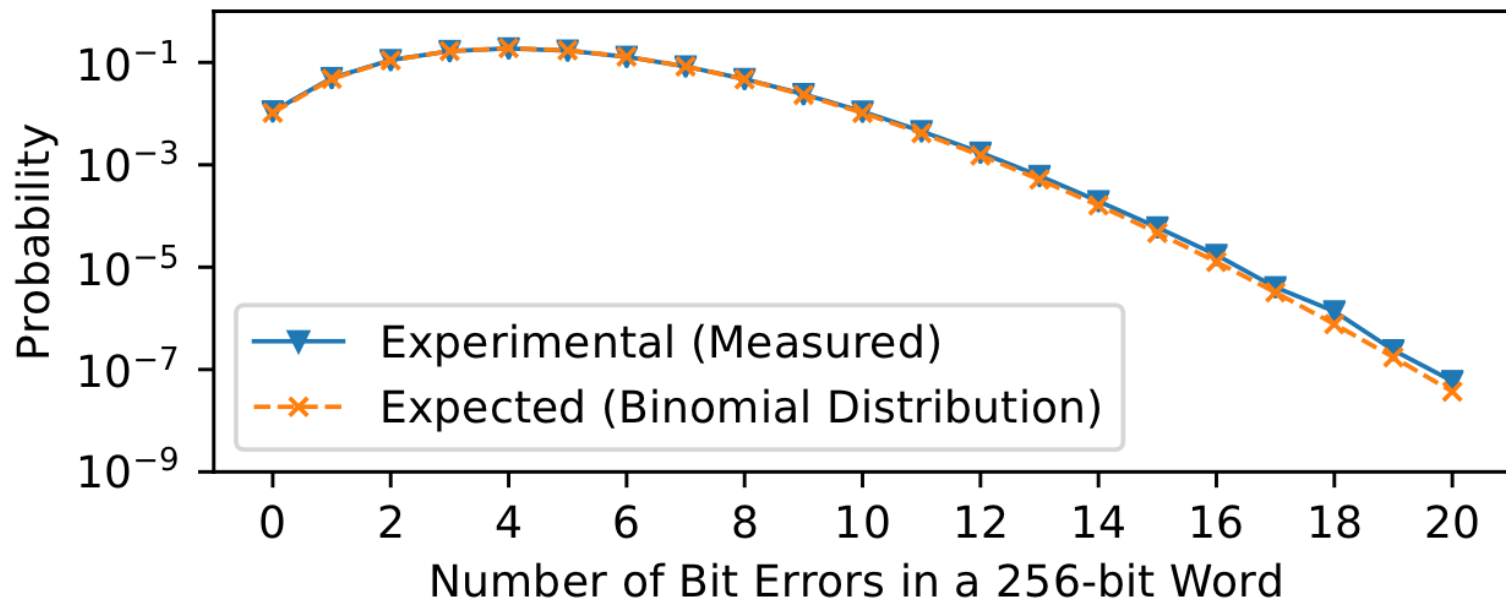
Error Checker



- Computes a configurable output distribution
 - Corresponds to the experimental measurement we make
 - E.g., number of errors per dataword (i.e., $\overline{w_N}$)

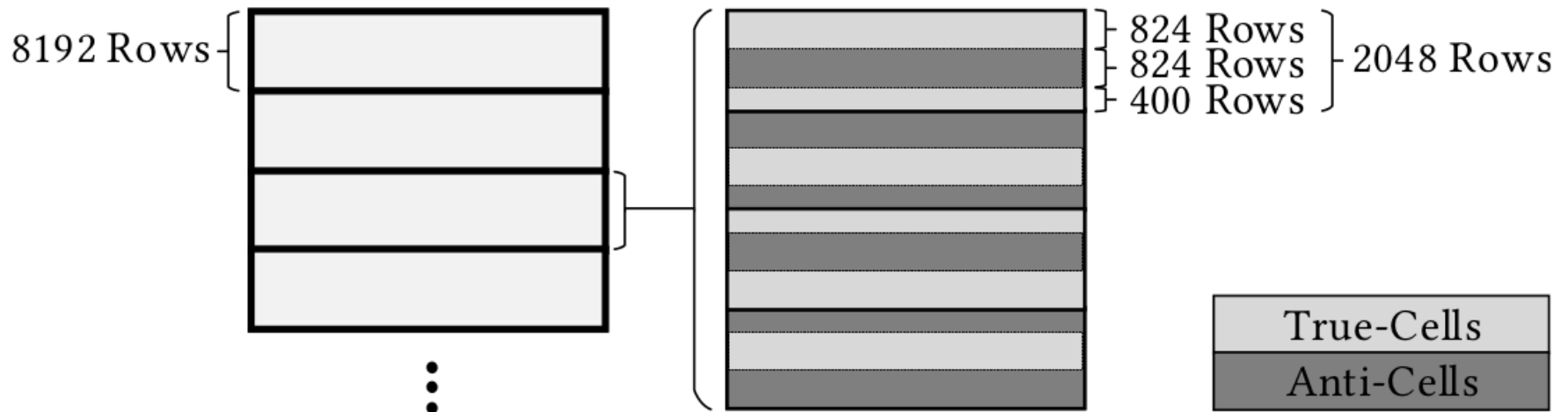
Validating Uniform-Randomness

- We model data-retention errors as **uniform random**
 - Well-studied throughout prior work
 - Error count per N-bit word follows a **binomial distribution**
- We experimentally validate uniform-randomness
 - 82 LPDDR4 devices **without** on-die ECC
 - Disable refresh operations for 20s @ 60°C



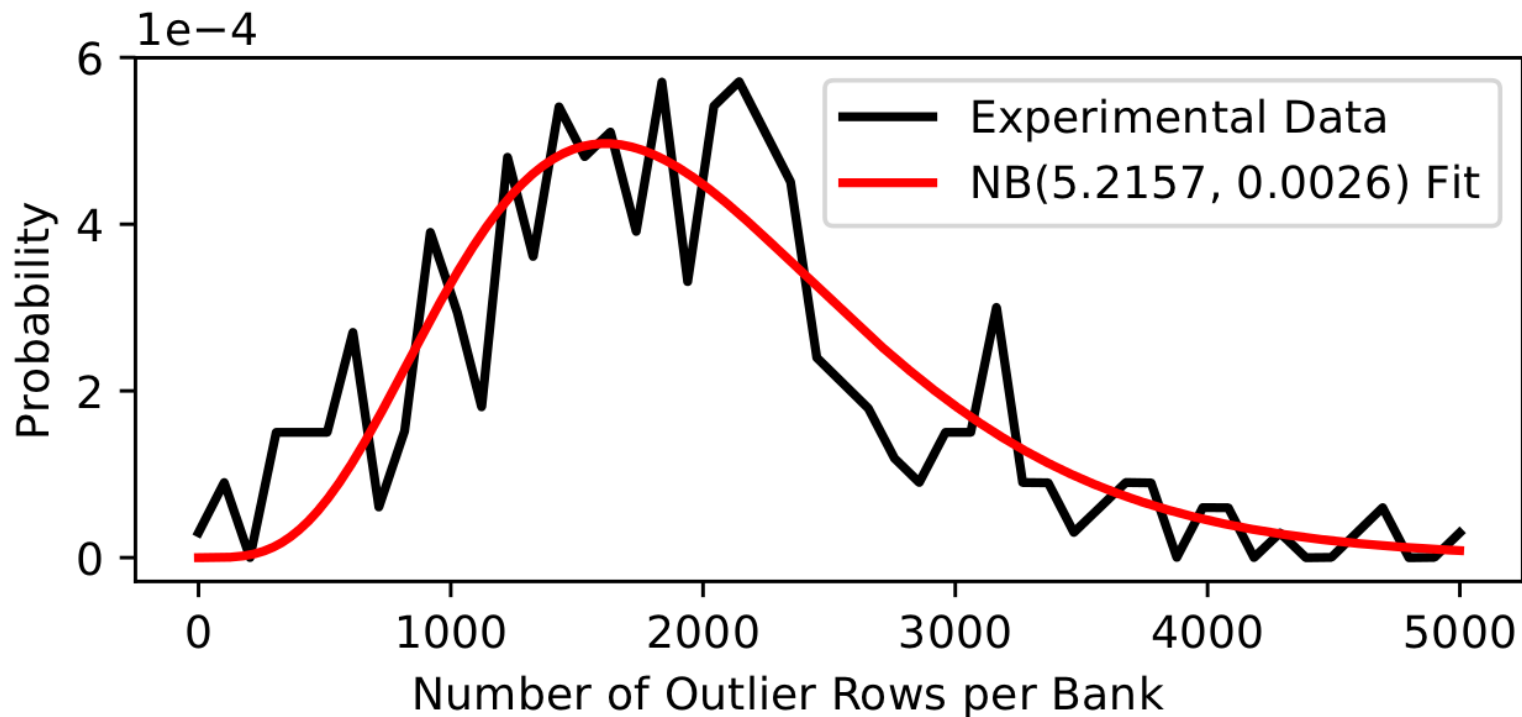
Anatomy of a DRAM Bank

- DRAM cells can encode data in two ways:
 - Data '1' as 'charged' -> "True-cell"
 - Data '1' as 'discharged' -> "Anti-cell"
- Retention errors typically "charged" -> "discharged"

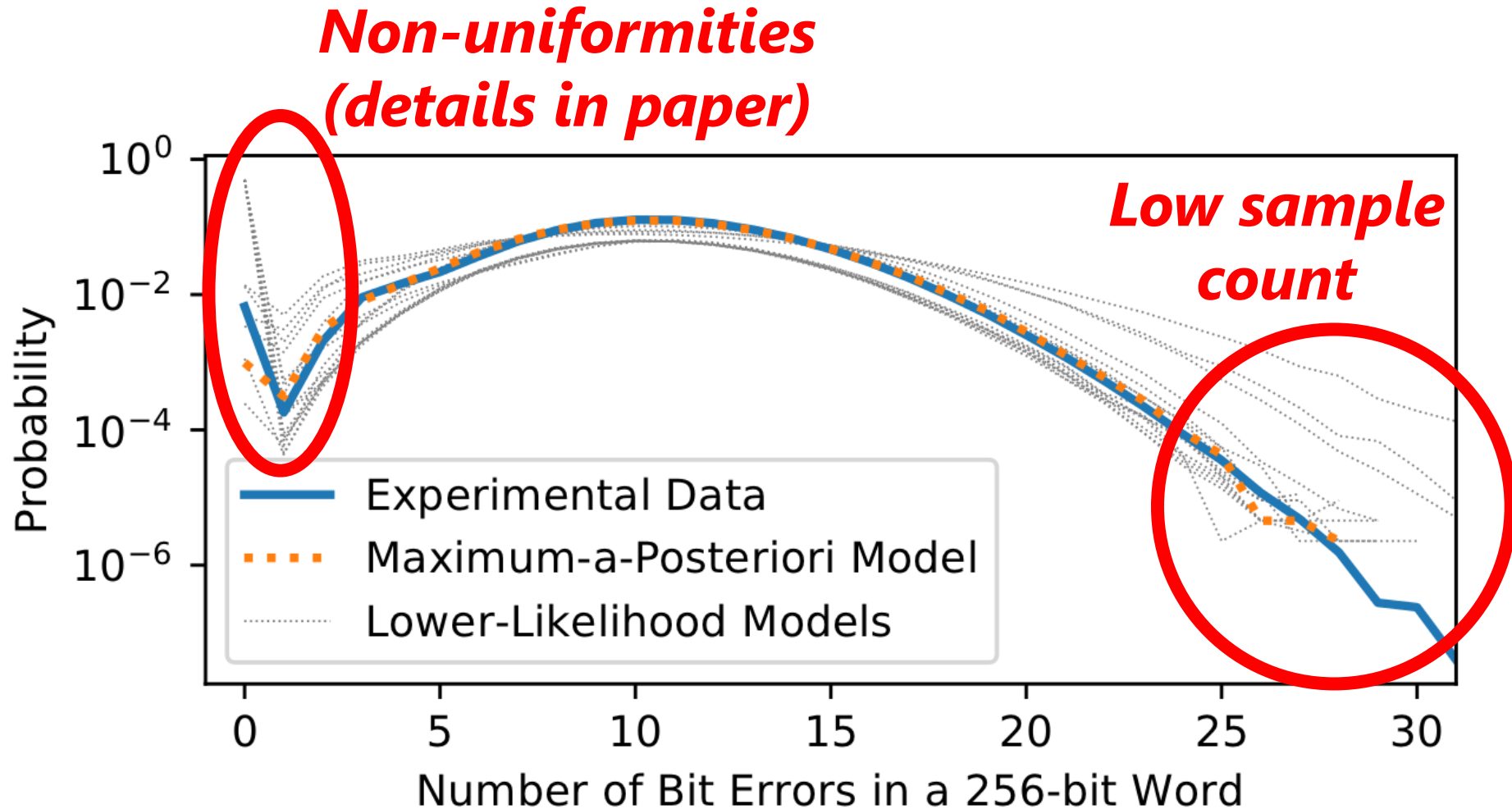


Incidence of “Outlier Rows”

- Some rows do not follow the true-/anti-cell layout
- Appear to follow typical “remapped row” distributions
 - Extra memory rows used for post-manufacturing repair



MAP Estimation Shown Graphically



Example Error-Characterization Studies

- We provide two studies to demonstrate EIN's value
 - Measure data-retention error rates
 - Have 314 LPDDR4 devices (with + without on-die ECC)
- 1. BER vs. refresh rates
 - We compare devices with on-die ECC to those without it
 - EIN infers the *pre-correction* BER beneath on-die ECC
 - Enables comparing BER of the DRAM technology itself
- 2. BER vs. temperature
 - On-die ECC distorts the expected exponential relationship
 - EIN recovers the obfuscated statistical distribution

Finding the “Right” Answer

- MAP estimation selects between suspected models
 - EIN cannot tell if the MAP estimate is “right”
 - “Likelihood” is a relative measure
- 1. Techniques for gaining confidence in the answer:
 - Using confidence intervals (e.g., statistical bootstrap)
 - Testing across many different error conditions
- 2. Unlikely that the ECC scheme used is unknown
 - ECC is a well-studied area
 - Manufacturers are unlikely to a completely unknown code
- 3. Typically we may suspect some schemes already
 - Academic/industry papers, datasheets, etc.

Control of Errors

- EIN requires *knowledge* and *control* of errors
 1. Understand the spatial distribution of errors
 2. Be able to induce uncorrectable errors
- Not a limitation in practice for DRAM
 - Many well-studied easily-controlled error mechanisms exist
 - E.g., data retention
 - E.g., access-latency reduction (i.e., tRCD, tRP, etc.)
 - E.g., RowHammer

Error Localization

- EIN cannot identify *bit-exact* error locations
 - ECC decoding function is *lossy* (i.e., many-to-one)
 - We are unaware of a way to reverse the decoding function
- Not a limitation in practice since we can still infer:
 - The ECC scheme
 - Pre-correction error rates